

# GCT Camera Progress

Jon Lapington, CTA Consortium Meeting, Turku, May 2015



### **GCT: The Gamma Cherenkov Telescope**

#### ⊙ Talks at this meeting:

Monday SST

• SST configuration 3: GCT

#### Tuesday SST

- GCT structure and optics
- GCT MC Studies
- Control of GCT camera peripherals
- GCT Camera Progress
- GCT Camera Software
- GCT Calibration
- Thursday Plenary
  - SST-2M GCT progress report
  - CHEC progress report

# **GCT: The Gamma Cherenkov Telescope**

Contents:

- Ocamera team evolution
- ⊙CHEC-M
  - > Overview
  - Mechanics
  - Electronics
  - Commissioning
  - Auxiliary Systems
- ⊙CHEC-S and beyond
  - ➢ SiPMs
  - Front-end electronics
- ⊙ Summary



#### **Evolution of the camera team**

#### UK collaboration

Leicester, Durham, Liverpool, Oxford, Liverpool John Moores (2015)

- ⊙ 1<sup>st</sup> STFC funding 04/2012 03/2015, PI Jim Hinton
- ⊙ March 2015: Jim, Rich, Akira  $\rightarrow$  MPIK, Heidelberg
- Proposed STFC funding 2015-2017, PI Tim Greenshaw
- ⊙ Main camera development remains at Leicester
  - ➤ Jon Lapington lead (since 1<sup>st</sup> April 2015)
  - Duncan Ross mechanics
  - Julian Thornhill electronics
  - Pippa Molyneux commissioning
  - External team
    - Rich White, Akira Okumura, Arnim Balzer, Andrea De Franco, Jason Watson, Manuel Kraus, Tom Armstrong
- ⊙ Lab reorganization

CHEC-M, CHEC-S, GCT assembly & commissioning

#### **CHEC-M** in context

- First GCT camera prototype
- Properties:
  - > MAPMs
  - TARGET 5 ASICs
- To be installed on GATE later this year
- ⊙ The next step is CHEC-S
- Properties:
  - ≻ SiPMs
  - ≻ TARGET 7 ASICs
- → GCT pre-production camera
  > SiPMs (LCT5, etc.)
  - ➤ TARGET-C & TARGET-CCTV











Connections to lid assembly

#### **Electronics and Readout**





#### **Electronics and Readout**



#### **CHEC-M Camera Module**



## **CHEC-M Backplane**



### **CHEC-M Backplane**

#### • Hardware complete – firmware under development



Trigger FPGA

# **CHEC-M Backplane**



Connection to DACQs

Power to TARGET modules

> Accommodates TARGET modules in identical way to real Backplane

- Lab tests proceeding with a proto-Backplane
- All tests apart from triggering possible

Trigger and CLK input & fan-out

PSU and \_\_\_\_\_ switch box



# **CHEC-M DACQ Boards**

- University of Amsterdam & Seven Solutions:
  - 5 boards for manufactured, 2 iterations, both work, 2 for CHEC-M
- 2 boards provide:
  - 36 port switch
  - 4 x 1 Gb/s uplinks
  - Absolute time synchronisation (using White Rabbit)





# **CHEC-M** Calibration Units

- Illumination of the focal plane via reflection from the secondary mirror
- Installed in each corner of the camera
- Performance:
  - Multi-LED provides ~1 1000 pe
  - Pulse width ~4 ns





# **CHEC-M Mechanics**

- Machined and bent Aluminum
- Defocus of 1 mm → PSF degradation of 10% (on axis)
  - Achieve ~0.35 mm spread between MAPM centres with no adjustment
  - Can be reduced to 0.035 mm





# Assembly

- Internal rack built
- Focal plane attached
- Backplane and DACQ boards attached
- ⊙ TMs inserted









# Assembly

#### ⊙ TMs pulled in from rear

- TARGET module inserted into slot in rack until screw mates with standoff
- TARGET module pulled into place with screw via tool inserted through backplane access hole
- TARGET module fully mated with backplane and secured in place
- Pre-amps secured from front
- MAPMs added

.

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Enclosure added



#### **Commissioning Lab Setup**

Initial setup for uniform illumination





### **Commissioning Lab Setup**





# **Commissioning Lab Setup**





#### **Camera Readout**

- Raw data and slow control over 4 x 1 Gbps
- Camera Server and Camera Controller software running as separate processes on 1 PC
- ⊙ Camera Server
  - Listens for raw data, builds events, writes to disk (binary format stored in fits files, with protobuf headers)
  - Receives run start / stop messages from Camera Controller

#### Camera Controller

- Reads in camera config (protobufs)
- Setups up the hardware (UDP raw socket to TM, zmq to DACQs)
- Signals run start / stop to Camera Server and sends run header
- Monitors camera (e.g. temperature) and writes to a fits file with time stamps
- Offline
  - > Analysis chain, uses same protobuf structure for headers / config as online
  - Assembles slow control and raw data based on timestamps
- A lot of manpower has gone into this: libCHEC, see Andrea's talk next...

# **Commissioning Progress**



# **Auxiliary Systems**

#### • PSU

- Located behind M2
- Identical to the one being used in the lab
- Chiller
  - Cooling loop now tested in Leicester



Ethernet controllable





### **CHEC-S**

- See previous meetings for overview
- Latest news:

51.4 mm

- TARGET-7 modules under test at ECAP
- Last part of SiPM tile delivery delayed
- Front-end buffer and preamp now under test at Leicester with full SiPM tile attached to base

4 pixels combined to make 1

CHEC-S

pixel

CHEC-S SiPM:

Hamamatsu S12642-1616PA-50

51.4 mm

64 camera pixels

87% geometric fill factor

 93% geometric fill factor possible with 6

mm x 50 mm

mm pixels and same

gaps, tile reduces to 50

Depth of ~3.5 mm

(including base PCB)



3 mm

0.2-mm Gap

Through Silicon Via (TSV)

50-µm Cells with

**Thin-Film Coating** 

Micro coax cables

#### **CHEC-S**

- Front end buffer tests
- ⊙ Only using mechanical samples thus far
- Faster pulse rise time than previous devices
- Ideal pulse requires more than p/z correction



SiPM tile, base and front-end buffer test in dark box



Preamp response with 1 pixel



Preamp response with 4 pixels

#### **CHEC-S**

#### ⊙ SiPM – epoxy coating requested

- Not supplied by Hamamatsu
- Thin (paralene?) coating only
- No waterproofing
- Camera window required
- Borofloat-33 glass
  - Not obtainable thin enough
- Shinkolite plastic
  - Not obtainable thin enough
- ⊙ PMMA Polycasa XT-UVT
  - Thermal forming or blow moulding
  - > 2mm thick  $\rightarrow$  82% trans.
  - But high thermal expansion
  - Need flexible seals

### **Beyond CHEC-S**

- Onventional front-end electronics options
  - CHEC-S discrete solution (integrated near sensor)
  - Existing TARGET7 daughterboard design
- PACTA chip ICC-UB
  - Multichannel ASIC front-end electronics
  - Initially developed for LST/MST
  - Designed for SiPMs (high capacitance)
  - Integrated additional functionality for SST
- TARGET-C and TARGET-CCTV
  - > Substrate noise  $\rightarrow$  2 separate ASICs required
- Latest SiPMs?
  - Technology still improving
  - No imp. from Hamamatsu after LCT5
  - Other manufacturers still viable
  - Larger pixel size



### Summary

- CHEC-M commissioning in progress
- Full testing limited by BP delay
  - ..but delivery imminent
- Meudon field trials
  - ➤ Later in 2015
- ⊙CHEC-S progressing
  - First batch MPPCs delivered
  - ..and will be attached to PCBs next
  - Second MPPC batch due end-May

